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19950113

CPY - MODE-N

- SUMB

DC - A18 A85 G03 L03 U11

FS - CPI;EPI

IC - C09J7/02 ; H01L21/301

MC - A04-F01A A07-A04E A08-C01 A08-M05 A10-E24 A11-C02B A12-E07C G03-B02D1
G03-B02E4 G03-B04 L04-C17D

- U11-A09

PA - (MODE-N) MODERN PLASTIC KOGYO KK

- (SUMB) SUMITOMO BAKELITE CO LTD

PN - JP3035179B2 B2 20000417 DW200024 C09J7/02 011pp

- JP8188757 A 19960723 DW199639 C09J7/02 011pp

PR - JP19950003676 19950113

XA - C1996-122562

XIC - C09J-007/02 ; H01L-021/301

XP - N1996-327423

AB - J08188757 A pressure sensitive adhesive sheet (P) for processing semiconductor wafers has a base material sheet (A), which UV rays and/or radiation can transmit and at least one pressure sensitive adhesive layer (B), which cures by polymerizing by being irradiated with UV rays and/or radiation and (B) has been formed from pressure sensitive adhesive compsn. contg. 0.05-15 pts. wt. of crosslinking agent (B2), 30-150 pts. wt. of polyfunctional urethane acrylate oligomer (B3), 0.03-22.5 pts. wt. of photoinitiator (B4), 1-30 pts. wt. of tackifier resin (B5) to 100 pts. wt. of acrylic polymer (B1).

- USE - (P) can be suitably used in processing of semiconductor wafers.

- ADVANTAGE - (P) is excellent in stretchability and stress relaxation properties and so hardly causes local stress concn. Additionally adhesion strengths to semiconductor wafers before and after irradiation of UV rays or radiation (e.g. 200-300 g/25 mm before irradiation and 20-25 g/25 mm after irradiation) do not change even after long exposure to heat or fluorescent lamp.

- (Dwg.0/0)

IW - PRESSURE SENSITIVE ADHESIVE SHEET PROCESS SEMICONDUCTOR WAFER BASE SHEET CAN TRANSMIT ULTRAVIOLET RAY RADIATE PRESSURE ADHESIVE LAYER

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NC - 001

OPD - 1995-01-13

ORD - 1996-07-23

PAW - (MODE-N) MODERN PLASTIC KOGYO KK

- (SUMB) SUMITOMO BAKELITE CO LTD

TI - Pressure sensitive adhesive sheet for processing semiconductor wafers

- has base sheet which can transmit UV rays and/or radiation and pressure adhesive layer(s)

A01 - [001] 018 ; R00326 G0044 G0033 G0022 D01 D02 D12 D10 D51 D53 D58 D82 ;

R00964 G0044 G0033 G0022 D01 D02 D12 D10 D51 D53 D58 D83 ; R00338

G0544 G0022 D01 D12 D10 D51 D53 D58 D69 D82 C1 7A ; H0000 ; S9999

S1581 ; P1150 ; P1796 P1809 ; P1161 ; P1343 ;
 - [002] 018 ; H0022 H0011 ; R00326 G0044 G0033 G0022 D01 D02 D12 D10
 D51 D53 D58 D82 ; G0055-R G0044 G0033 G0022 D01 D02 D12 D10 D51 D53
 D84 ; S9999 S1581 ; P1150 ;
 - [003] 018 ; H0022 H0011 ; R00326 G0044 G0033 G0022 D01 D02 D12 D10
 D51 D53 D58 D82 ; R00835 G0566 G0022 D01 D11 D10 D12 D51 D53 D58 D63
 D84 F41 F89 ; S9999 S1581 ; P1150 ; P1310 ;
 - [004] 018 ; H0022 H0011 ; R00326 G0044 G0033 G0022 D01 D02 D12 D10
 D51 D53 D58 D82 ; R00936 G0044 G0033 G0022 D01 D02 D12 D10 D51 D53
 D58 D88 ; S9999 S1581 ; P1150 ;
 - [005] 018 ; H0022 H0011 ; R00326 G0044 G0033 G0022 D01 D02 D12 D10
 D51 D53 D58 D82 ; R02043 G0044 G0033 G0022 D01 D02 D12 D10 D51 D53
 D58 D86 ; S9999 S1581 ; P1150 ;
 - [006] 018 ; R00326 G0044 G0033 G0022 D01 D02 D12 D10 D51 D53 D58 D82 ;
 G0055-R G0044 G0033 G0022 D01 D02 D12 D10 D51 D53 D84 ; R00964 G0044
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 H0011 ; P1150 ;
 - [007] 018 ; P0884 P1978 P0839 H0293 F41 D01 D11 D10 D19 D18 D31 D50
 D63 D90 E21 E00 ; S9999 S1581 ;
 - [008] 018 ; ND01 ; Q9999 Q7476 Q7330 ; B9999 B3883 B3838 B3747 ;
 B9999 B5301 B5298 B5276 ; K9416 ;
 - [009] 018 ; B9999 B3907 B3838 B3747 ;
 A02 - [001] 018 ; H0022 H0011 ; G0340-R G0339 G0260 G0022 D01 D12 D10 D26
 D51 D53 D58 D63 F41 F89 G0384-R ; R00835 G0566 G0022 D01 D11 D10 D12
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 - [002] 018 ; H0022 H0011 ; R00446 G0282 G0271 G0260 G0022 D01 D12 D10
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 - [003] 018 ; H0022 H0011 ; R00460 G0306 G0271 G0260 G0022 D01 D12 D10
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 - [004] 018 ; ND01 ; Q9999 Q7476 Q7330 ; B9999 B3883 B3838 B3747 ;
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 - [005] 018 ; B9999 B5094 B4977 B4740 ; B9999 B4988-R B4977 B4740 ;
 K9869 K9847 K9790 ; B9999 B5243-R B4740 ;
 - [006] 018 ; A999 A179 A157 ; A999 A771 ;
 - [007] 018 ; A999 A680 ;
 A03 - [001] 018 ; P1592-R F77 D01 ; M9999 M2017 ; M9999 M2813 ; L9999
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 - [002] 018 ; ND01 ; Q9999 Q7476 Q7330 ; B9999 B3883 B3838 B3747 ;
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 B9999 B5243-R B4740 ;
 - [004] 018 ; A999 A179 A157 ; A999 A771 ;
 - [005] 018 ; A999 A680 ;
 A04 - [001] 018 ; D10-R D18-R ; A999 A782 ; A999 A680 ; P0602 D01 D02 ;
 - [002] 018 ; B9999 B5094 B4977 B4740 ;
 - [003] 018 ; B9999 B5629 B5572 ;